

Abstract of the Disclosure:

In an electronic component having a piezo-electric resonator 10 formed on an element substrate and obtaining a signal having a predetermined resonant frequency by a bulk wave propagating through a piezo-electric film, a packaging substrate 19 on which the piezo-electric resonator 10 is mounted by face-down bonding through bumps 18, and a lid 21 fixed on the packaging substrate 19 and sealing the piezo-electric resonator 10, a distance between a surface of the piezo-electric resonator 10 facing said packaging substrate 19 and a surface of the packaging substrate 19 facing the piezo-electric resonator 10 is not larger than 100 μm . A maximum diameter of the bump 18 is not larger than 150 μm , when the bump 18 is connected to the packaging substrate 19. A distance between a surface of the piezo-electric resonator 10 facing the lid 21 and a surface of the lid 21 facing the piezo-electric resonator 10 is not larger than 150 μm .

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